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ATF-44100 (AT-8141) 2-8 GHz Medium Power **Gallium Arsenide FET** 



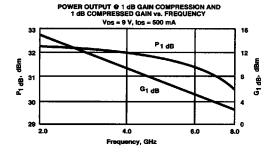
#### **Features**

- **High Output Power:** 32.0 dBm typical P1 dB at 4 GHz
- High Galn at 1 dB Compression: 9.0 dB typical G<sub>1 dB</sub> at 4 GHz
- **High Power Efficiency:** 36% typical at 4 GHz

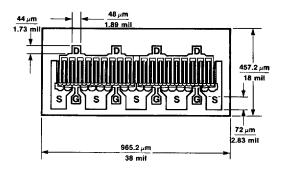
### **Description**

The ATF-44100 is a gallium arsenide Schottky-barrier-gate field effect transistor designed for medium power, linear amplification in the 2 to 8 GHz frequency range. This nominally 0.5 micron gate length GaAs FET is an interdigitated four-cell structure using airbridge interconnects between source fingers. Total gate periphery is 5 millimeters. Proven gold based metallization systems and nitride passivation assure a rugged, reliable device.

The recommended mounting procedure is to die attach at a stage temperature of 300° C using a gold-tin preform under forming gas. Assembly should be performed with wedge bonding using either 0.7 mil of 1.0 mil gold wire. See also "Chip Use" in the APPLICATIONS section.



## Chip Outline



## Electrical Specifications, TA = 25°C

Symbol	Parameters and Test Conditions <sup>1</sup>	Units	Min.	Тур.	Max.	
P1 dB	Output Power @ 1 dB Gain Compression: VDS = 9 V, IDS = 500 mA	f = 4.0 GHz f = 6.0 GHz f = 8.0 GHz	dBm		32.0 31.5 31.0	
G1 dB	1 dB Compressed Gain: VDS = 9 V, IDS = 500 mA	f = 4.0 GHz f = 6.0 GHz f = 8.0 GHz	₫B	8.0	9.0 6.0 3.0	
ηadd	Efficiency @ P1 dB: VDS = 9 V, IDS = 500 mA	f = 4.0 GHz	%		36	
gm	Transconductance: VDS = 2.5 V, IDS = 500 mA	•	mmho		300	
IDSS	Saturated Drain Current: VDS = 1.75 V, VGS = 0 V		mA	800	1300	1500
VP	Pinchoff Voltage: VDS = 2.5 V, IDS = 5 mA		V	-5.4	-4.5	-2.0

Note: 1. RF Performance is determined by assembling and testing 10 samples per wafer.

ATF-44100, 2-8 GHz Medium Power Gallium Arsenide FET

# HEWLETT-PACKARD/ CMPNTS

Absolute	Maximum	Ratings
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Parameter	Symbol	Absolute Maximum¹		
Drain-Source Voltage	VDS	+14 V		
Gate-Source Voltage	VGS	-7 V		
Drain Current	los	IDSS		
Power Dissipation <sup>2,3</sup>	P⊤	8.3 W		
Channel Temperature	ТСН	175°C		
Storage Temperature	Тѕтс	-65°C to +175°C		

Thermal Resistance:  $\theta_{jc} = 18^{\circ}$ C/W; TCH = 150°C Liquid Crystal Measurement; 1  $\mu m$  Spot Size<sup>4</sup>

#### Notes:

- Operation of this device above any one of these parameters may cause permanent damage.
- 2. Mounting Surface Temperature = 25°C.
- 3. Derate at 55.6 mW/°C for TMOUNTING SURFACE > 26°C.
- The small spot size of this technique results in a higher, though more accurate determination of θ<sub>ic</sub> than do alternate methods. See MEASUREMENTS section for more information.

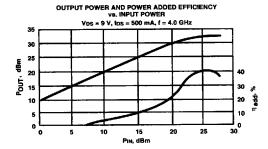
## Part Number Ordering Information

Part Number	Devices Per Tray				
ATF-44100-GP1	5				
ATF-44100-GP3	50				
ATF-44100-GP6	up to 300				

Typical Performance, T<sub>A</sub> = 25°C

(unless otherwise noted)

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Typical Scattering Parameters: Common Source, $Z_0 = 50 \Omega$						Ω	$T_A = 25^{\circ}C$ , $V_{DS} = 9 V$ , $I_{DS} = 500 m$					
Freq. GHz	S <sub>11</sub>		S <sub>21</sub>				S <sub>12</sub>			S <sub>22</sub>		
	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang	Mag	Ang		
1.0	.88	-117	13.1	4.52	111	-28.0	.040	34	.37	-162		
2.0	.89	-149	8.1	2.55	88	-26.0	.050	36	.41	-168		
3.0	.89	-163	5.1	1.80	72	-25.4	.054	38	.44	-170		
4.0	.90	-172	2.4	1.32	60	-24.7	.058	44	.47	-173		
5.0	.91	-179	0.3	1.04	49	-24.3	.061	46	.52	-176		
6.0	.92	175	-1.4	.85	39	-23.5	.067	47	.56	-178		
7.0	.92	170	-3.2	.69	30	-23.0	.071	49	.60	180		
8.0	.93	167	-44	.60	24	-22.6	.074	50	.64	176		
9.0	.93	162	-5.7	.52	15	-22.2	.078	51	.67	175		
10.0	.94	158	-6.7	.46	10	-21.7	.082	52	.70	173		
11.0	.95	153	-7.7	.41	3	-21.3	.086	50	.73	172		
12.0	.95	145	-9.1	.35	-4	-20.7	.092	49	.76	171		

A model for this device is available in the DEVICE MODELS section.